October 3th, 2025

PMMI
The Association for Packaging
and Processing Technologies

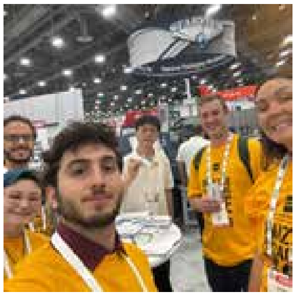
Show News

Team 7 Takes the Show Floor by Storm in the 2025 Amazing Packaging Race at PACK EXPO Las Vegas

Students from across the nation showcase their talent in an adrenaline-pumping competition of speed and strategy at PACK EXPO Las Vegas.

October 3, 2025

Las Vegas, NV; October 3, 2025 — The show floor at PACK EXPO Las Vegas was palpable with energy on Wednesday, as the 2025 Amazing Packaging Race winners were revealed. Organized by PMMI, The Association for Packaging and Processing Technologies, and proudly sponsored by Emerson Discrete Automation, this year's event brought together 27 college and university student teams from across the U.S. in an action-packed competition of speed, strategy, and creativity.



Team 3 – Using the Starview SB-PH1-1012 Manual Shuttle

Navigating the expansive PACK EXPO Las Vegas show floor, Team 7 took the competition by storm, demonstrating exceptional teamwork, problem-solving, and industry knowledge—capturing first place. Comprised of Joseph Delaughter (Clemson University), Kirkley Fallaw (Clemson University), Landry Feldman (Rochester Institute of Technology), Kyle Feng (California Polytechnic State University), and Ray Flannagan (Virginia Tech), the team impressed judges and exhibitors alike with its ability to master quick-thinking challenges and engage with exhibitors in innovative ways. Each team member was awarded $1,000.

In second place, close on the heels of the winners, Team 6 delivered a fierce challenge in a down-to-the-wire finish. Made up of Jordan D'Amario (Michigan State University), Khaliun Dashdavaa (California Polytechnic State University), Alec Davis (Clemson University), Sinyee de Cleir (Rochester Institute of Technology), and Sophia Deal (Virginia Tech), their sharp focus and strong teamwork made them stand out as memorable competitors. Each team member was awarded $500.

Rounding out the competition in third place is Team 2. Made up of Meyhun Bhatt (Virginia Tech), Jenna Bovenzi (Rochester Institute of Technology), Cayden Bowe (Tuskegee University), Parker Braun (University of Wisconsin–Stout), and Lincey Chu (Virginia Tech), the team showed great tenacity and ability to make it to the top three out of 27 total competitors and will be one to watch in future races. Each team member was awarded $250.

“The Amazing Packaging Race gives students an unforgettable opportunity to apply their classroom learning in real-world scenarios, while engaging directly with the companies that are driving innovation in our industry,” says Kate Torrence, director of workforce development, PMMI. “We're always amazed by the energy, excitement, and talent these students bring to PACK EXPO. It's exciting to see what the future holds in store for our industry through tomorrow's leaders.”

“As a multi-year sponsor of the Amazing Packaging Race, Emerson always looks forward to supporting these extraordinary students,” says Nick Buccheri, President, Discrete Automation Americas at Emerson. “The energy, wit, and determination they bring to the floor is inspiring. They remind us why the future of packaging and processing is so bright.”

The Amazing Packaging Race would not have been possible without the support of participating exhibitors who hosted challenges and were at their booths during the event.

The 2025 participating exhibitors included:

- Beckhoff Automation
- Carleton Helical Technologies
- CMCO Conveyance Solutions
- Cold Pressure Council
- Domino North America
- Econocorp
- Encoder Products Company
- Fallas Automation Inc.
- Formers International, Inc.
- FOX IV Technologies, Inc.
- HARPAK-ULMA Packaging, LLC
- Hoosier Feeder
- IoPP
- Lenze Americas
- LinMot USA
- Massman Companies
- Morrison Container Handling Solutions
- NVenia, a Duravant Company
- OMAC
- Pacteon Group
- Pepperl+Fuchs, Inc.
- Promach
- Rinco Ultrasonics USA
- Shurtape Technologies
- SICK, Inc.
- Siemens Digital Industries
- Starview Packaging Machinery
- Triangle Package Machinery Company

Competing students represented leading schools and universities from across the country. For many, the race served as an opportunity to gain hands-on experience, expand professional networks, and explore future careers in packaging and processing.

PMMI looks forward to welcoming students once again to the Amazing Packaging Race in 2026 at PACK EXPO International in Chicago. To learn more about PMMI's Student Opportunities at PACK EXPO, visit **pmmi.org/workforce**.

Gatwiri Muthara
Sr. Manager, Public Relations
PMMI
571.485.8711
gmuthara@pmmi.org

Thank you to the PMMI Foundation Benefactor